

30V P-Channel Trench MOSFET(Preliminary)

General Description

- Trench Power technology
- Low R_{DS(ON)}
- Low Gate Charge
- Optimized for fast-switching applications
- Qualified for industrial applications according to the relevant tests of JESD47

Applications

- Synchronous Rectification in DC/DC and AC/DC Converters
- Isolated DC/DC Converters in Telecom and Industrial

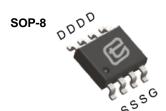
Product Summary

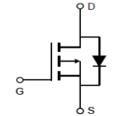
 V_{DS} -30V I_{D} (at V_{GS} =-10V) -12A

$$\begin{split} R_{DS(ON)} \; (at \; V_{GS} = -10 V) & < 18.5 m \Omega \\ R_{DS(ON)} \; (at \; V_{GS} = -4.5 V) & < 30.5 m \Omega \end{split}$$

100% UIS Tested







Part Number	Package Type	Form	Marking
TTJ12P03AT	SOP-8	Tape & Reel	12P03AT

Absolute Maximum Ratings (T_A =25°C unless otherwise noted)

Parameter		Symbol	Maximum	Units
Drain-Source Voltage		V _{DS}	-30	V
Gate-Source Voltage		V _{GS}	±20	V
Continuous Drain Current B	T _C =25°C	- I _D	-12	Δ.
Continuous Drain Current B	T _C =70°C		-9.6	А
Pulsed Drain Current A		I _{DM}	-36	А
Avalanche Current A		I _{AS}	-22	А
Single Pulse Avalanche Energy L =0.3mH A		E _{AS}	72.6	mJ
Dower Discipation C	T _C =25°C	- P _D	4	W
Power Dissipation ^C	T _C =70°C		2.5	W
Junction and Storage Temperature Range		T_J , T_{STG}	-55 to 150	°C
Thermal Characteristics				

Thermal Characteristics

Parameter		Symbol	Maximum	Units	
Maximum Junction-to-Lead	Steady-State	$R_{\Theta JL}$	25	00.004	
Maximum Junction-to-Ambient	Steady-State	$R_{\Theta JA}$	31	°C/W	



Electric	cal Characteristics(T _J =25°C ur	nless otherwise r	noted)				
Cumala al	Donomotor	Conditions		Value			11-24-
Symbol	Parameter	Conditions		Min	Тур	Max	Units
STATIC P	ARAMETERS				-		
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250 \mu A, V_{GS} = 0 V$		-30			V
		$V_{DS} = -30V, V_{GS} = 0V$	T _J =25°C			-1	μА
Zero Gate Voltage Drain Curre	Zero Gate Voltage Drain Current		T _J =125°C			-100	
I _{GSS}	Gate-Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 20V$	ı			±100	nA
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =-250μA		-1	-1.6	-2.4	V
		V _{GS} =-10V, I _D =-12A			15.5	18.5	mΩ
R _{DS(ON)}	Static Drain-Source On-Resistance	V _{GS} =-4.5V, I _D =-12A			25.5	30.5	mΩ
g _{FS}	Forward Transconductance	V _{DS} =-5V, I _D =-12A			20		S
V _{SD}	Diode Forward Voltage	I _S =-12A, V _{GS} =0V				-1	V
I _S	Maximum Body-Diode Continuous Curre	ent ^B				-12	Α
DYNAMIC	PARAMETERS				!	!	
C _{iss}	Input Capacitance				1973		
C _{oss}	Output Capacitance	$V_{GS} = 0V, V_{DS} = -15V, f$	=1MH _Z		222		pF
C _{rss}	Reverse Transfer Capacitance				195		
R_g	Gate Resistance	f =1MH _Z			5.4		Ω
SWITCHIN	NG PARAMETERS						
Q _g (10V)	Total Gate Charge				41		
Q _g (4.5V)	Total Gate Charge	10/// 15//	1 124		20		
Q_{gs}	Gate Source Charge	V _{GS} =-10V,V _{DS} =-15V, I _D =-12A			9		nC
Q_{gd}	Gate Drain Charge				6		
t _{D(on)}	Turn-On Delay Time				9		
t _r	Turn-On Rise Time	$V_{GS} = -10V, V_{DS} = -15V, I_{D} = -12A,$ $R_{G} = 2.5\Omega$			10		ns
t _{D(off)}	Turn-Off Delay Time				50		
t _f	Turn-Off Fall Time				20		
t _{rr}	Body Diode Reverse Recovery Time	1 _ 124 4:/4+ =1004/			24		ns
Q _{rr}	Body Diode Reverse Recovery Charge	$I_F = -12A$, di/dt = 100A/	μə		16		nC

- A. Single pulse width limited by maximum junction temperature.
- B. The maximum current rating is package limited.
- C. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

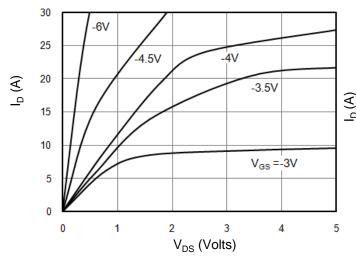


Figure 1: On-Region Characteristics

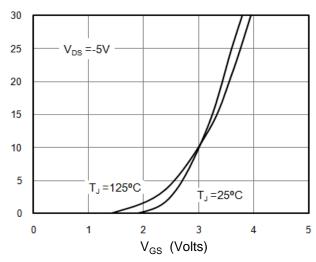


Figure 2: Transfer Characteristics

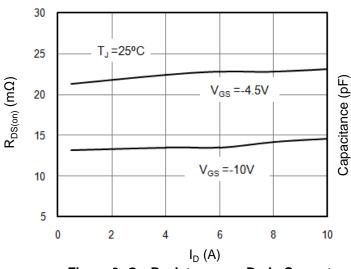


Figure 3: On-Resistance vs. Drain Current

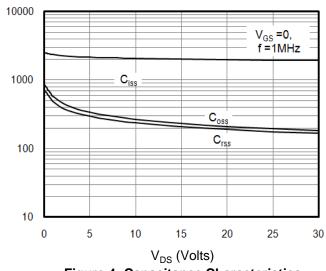


Figure 4: Capacitance Characteristics

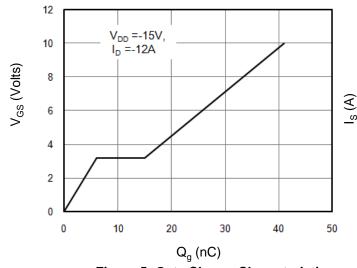


Figure 5: Gate Charge Characteristics

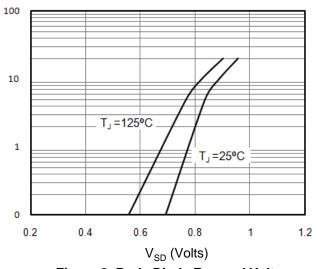
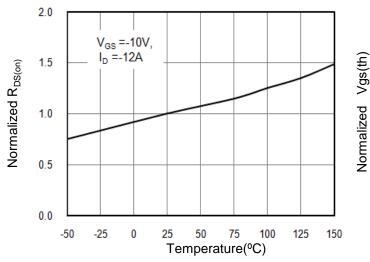


Figure 6: Body Diode Forward Voltage



 $Z_{\theta\, \text{JC}}$ Normalized Transient Thermal Resistance

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS



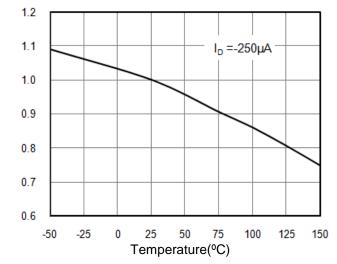
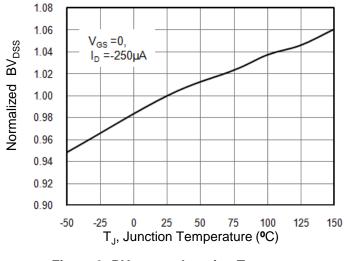


Figure 7: On-Resistance vs. Junction Temperature





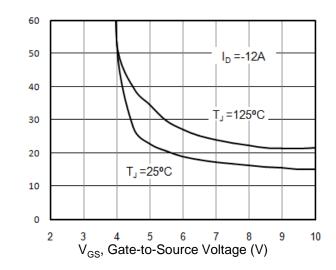
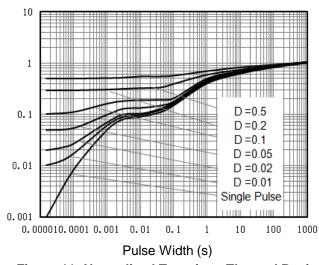


Figure 9: BV_{DSS} vs. Junction Temperature

Figure 10: On-Resistance vs. Gate-Source Voltage



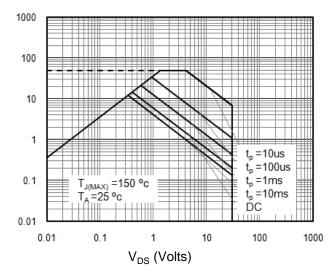


Figure 11: Normalized Transient Thermal Resistance

Figure 12: Safe Operating Area

 $R_{DS(on)}$ (m Ω)

l_D (Amps)

Figure A: Gate Charge Test Circuit and Waveform

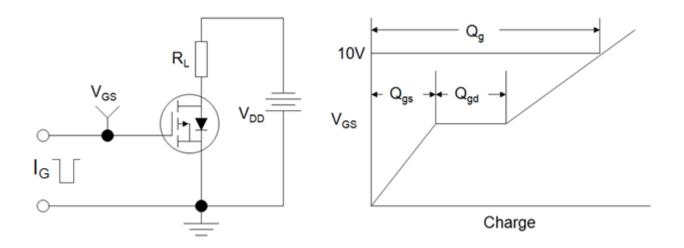


Figure B: Resistive Switching Test Circuit and Waveform

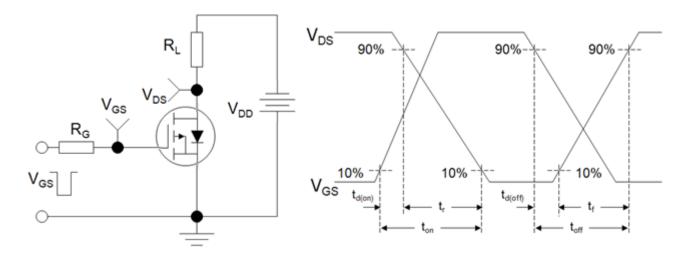
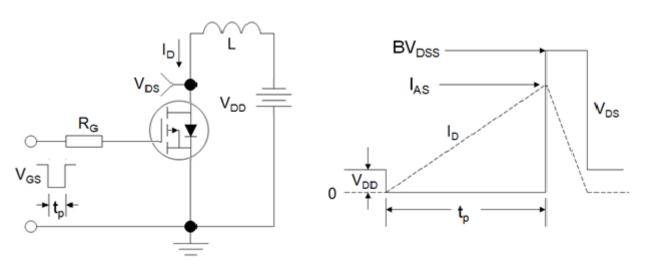


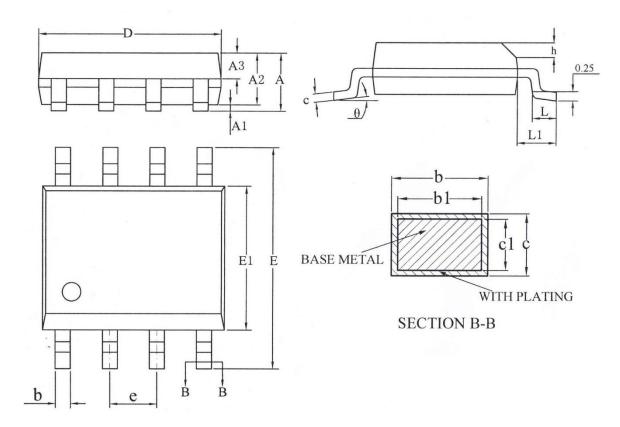
Figure C: Unclamped Inductive Switching Test Circuit and Waveform







SOP-8



SYMBOL	MILLIMETER				
	MIN	NOM	MAX		
A		_	1.75		
A1	0.10	_	0.225		
A2	1.30	1.40	1.50		
A3	0.60	0.65	0.70		
b	0.39	_	0.48		
bl	0.38	0.41	0.43		
С	0.21	_	0.26		
c1	0.19	0.20	0.21		

SYMBOL	MILLIMETER			
STMBOL	MIN	NOM	MAX	
D	4.70	4.90	5.10	
Е	5.80	6.00	6.20	
E1	3.70	3.90	4.10	
e	1.27BSC			
h	0.25	_	0.50	
L	0.50		0.80	
L1	1.05BSC			
θ	0		8°	



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